

N-CHANNEL 100V - 0.009 Ω - 140A MAX247™ MESH OVERLAY™ POWER MOSFET

VDSS	R _{DS(on)}	ID
100V	<0.011Ω	140A
	100V	

- TYPICAL $R_{DS}(on) = 0.009\Omega$
- STANDARD THRESHOLD DRIVE
- 100% AVALANCHE TESTED

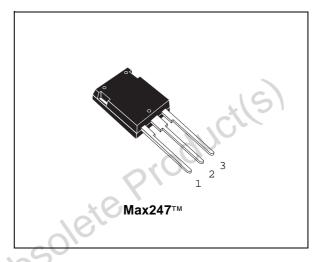
DESCRIPTION

Using the latest high voltage MESH OVERLAY[™] process, STMicroelectronics has designed an advanced family of power MOSFETs with outstanding performances. The new patent pending strip layout coupled with the Company's proprietary edge termination structure, gives the lowest RDS(on) per area, exceptional avalanche and dv/dt capabilities and unrivalled gate charge and switching characteristics.

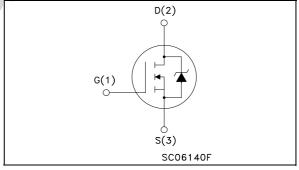
APPLICATIONS

- HIGH CURRENT, HIGH SWITCHING SPEED
- SWITCH MODE POWER SUPPLY (SMPS)

teprodu



INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage ($V_{GS} = 0$)	100	V
V _{DGR}	Drain-gate Voltage ($R_{GS} = 20 \text{ k}\Omega$)	100	V
V _{GS}	Gate- source Voltage	± 20	V
ID	Drain Current (continuos) at $T_C = 25^{\circ}C$	140	A
ID	Drain Current (continuos) at T _C = 100°C	99	A
I _{DM} (●)	Drain Current (pulsed)	560	A
P _{tot}	Total Dissipation at $T_C = 25^{\circ}C$	450	W
	Derating Factor	3	W/°C
E _{AS} (1)	Single Pulse Avalanche Energy	2900	mJ
dv/dt (2)	Peak Diode Recovery voltage slope	5	V/ns
T _{stg}	Storage Temperature	-55 to 175	°C
Ti	Operating Junction Temperature	-55 to 175	°C

August 2001

(1) Starting $I_j = 25$ °C, $I_D = 70A$, $V_{DD} = 50V$ (2) $I_{SD} \le 140A$, di/dt $\le 200A/\mu s$, $V_{DD} \le V_{(BR)DSS}$, $T_j \le T_{JMAX}$.

THERMAL DATA

Rthj-amb	Thermal Resistance Junction-case	Max	0.33	°C/W
	Thermal Resistance Junction-ambient	Max	30	°C/W
Тј	Maximum Lead Temperature For Soldering Purpose	Тур	300	°C

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	100			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V_{DS} = Max Rating V_{DS} = Max Rating T _C = 125°C			1 10	μΑ μΑ
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	$V_{GS} = \pm 20V$			±100	nA
ON (1)				00	.	

ON (1)

Symbol	Parameter	Test Co	onditions	Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I _D = 250 μA	2		4	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10 V	I _D = 70 A		0.009	0.011	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V _{DS} = 20 V I _D = 70 A		50		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{DS} = 25V, f = 1 MHz, V _{GS} = 0		12600 2100 690		pF pF pF
	je r	1		<u>I</u>		
SO						

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Delay Time Rise Time			40 150		ns ns
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V _{DD} =50V I _D =140A V _{GS} =10V (see test circuit, Figure 2)		450 70 170	600	nC nC nC

SWITCHING OFF

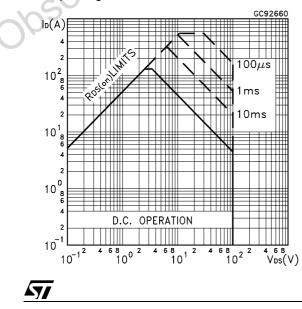
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(off)} t _f	Turn-off Delay Time Fall Time	$ \begin{array}{ll} V_{DD}=50 \ V & I_{D}=70 \ A \\ R_{G}=4.7\Omega, & V_{GS}=10 \ V \\ (\text{Resistive Load, Figure 1}) \end{array} $		465 270	JCr.	ns ns

SOURCE DRAIN DIODE

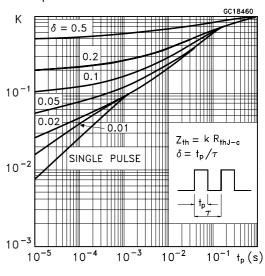
Symbol	Parameter	Test Conditions	Min. Typ.	Max.	Unit
I _{SD} I _{SDM} (●)	Source-drain Current Source-drain Current (pulsed)	6016		140 560	A A
V _{SD} (*)	Forward On Voltage	I _{SD} = 140 A V _{GS} = 0		1.5	V
t _{rr} Q _{rr} I _{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$ I_{SD} = 140 \text{ A} \qquad di/dt = 100 \text{A}/\mu\text{s} \\ V_r = 20 \text{ V} \qquad T_j = 150^\circ\text{C} \\ (\text{Inductive Load, Figure 3}) $		275 2 15	ns μC Α

(*)Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %.
(•)Pulse width limited by safe operating area.

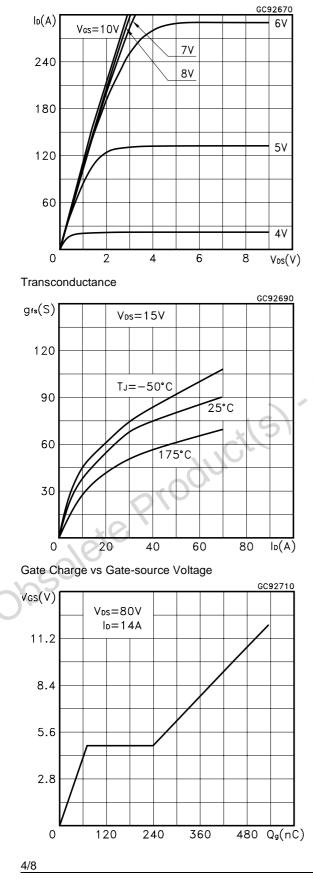
Safe Operating Area

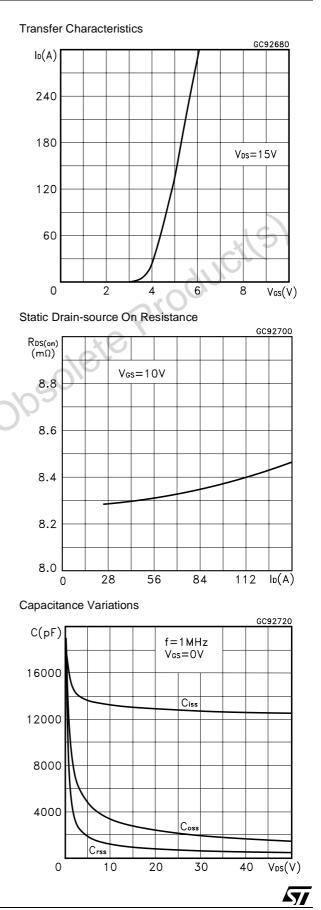


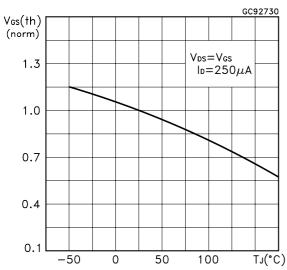
Thermal Impedance





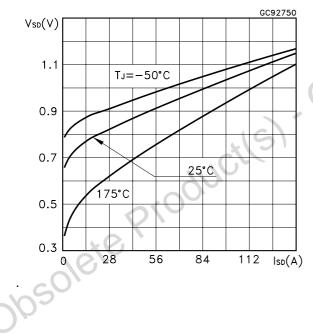




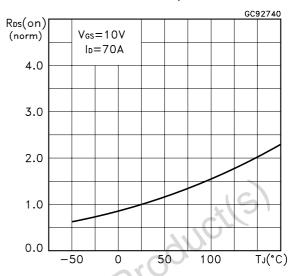


Normalized Gate Threshold Voltage vs Temperature

Source-drain Diode Forward Characteristics



Normalized on Resistance vs Temperature



Normalized Breakdown Voltage vs Temperature

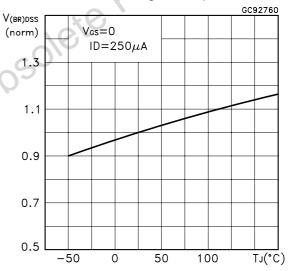


Fig. 1: Switching Times Test Circuits For Resistive Load

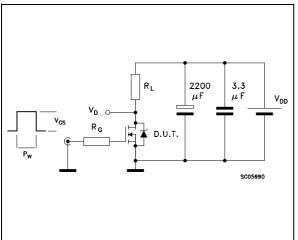


Fig. 3: Test Circuit For Diode Recovery Behaviour

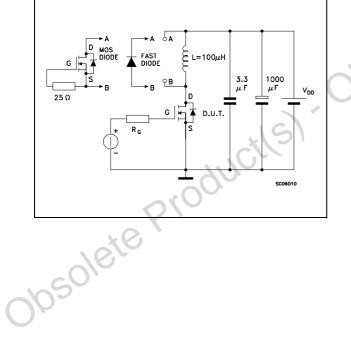
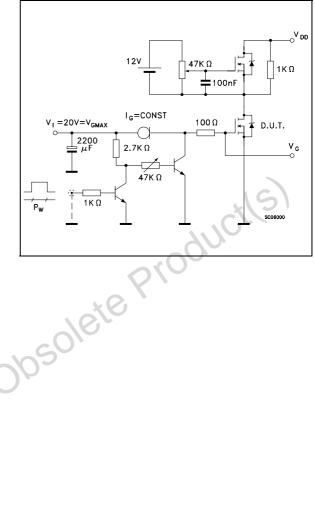


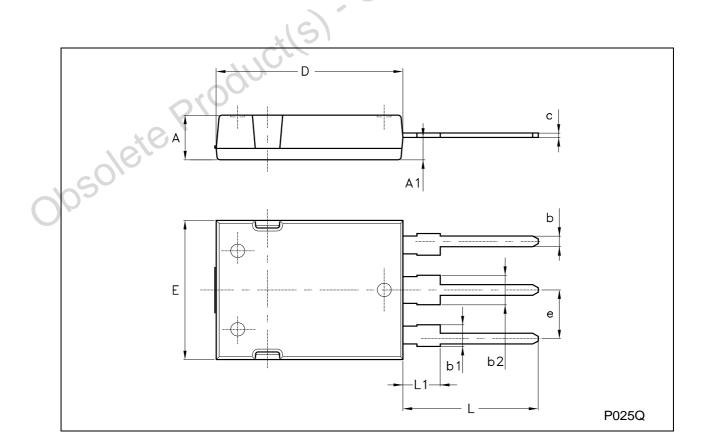
Fig. 2: Gate Charge test Circuit



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DIM.		mm			inch			
Dini.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.		
А	4.70		5.30					
A1	2.20		2.60					
b	1.00		1.40					
b1	2.00		2.40			IG		
b2	3.00		3.40			AC		
С	0.40		0.80		71)			
D	19.70		20.30					
е	5.35		5.55		210			
E	15.30		15.90	×C				
L	14.20		15.20	16,				
L1	3.70		4.30	0,				

Max247 MECHANICAL DATA





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